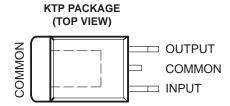
uA78Mxx-Q1 SERIES POSITIVE-VOLTAGE REGULATORS

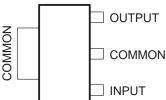
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- **Qualified for Automotive Applications**
- 3-Terminal Regulators
- **Output Current Up To 500 mA**
- **No External Components**



- **Internal Thermal-Overload Protection**
- **High Power-Dissipation Capability**
- **Internal Short-Circuit Current Limiting**
- **Output Transistor Safe-Area Compensation**

DCY (SOT-223) PACKAGE (TOP VIEW)



description/ordering information

This series of fixed-voltage integrated-circuit voltage regulators is designed for a wide range of applications. These applications include on-card regulation for elimination of noise and distribution problems associated with single-point regulation. Each of these regulators can deliver up to 500 mA of output current. The internal current-limiting and thermal-shutdown features of these regulators essentially make them immune to overload. In addition to use as fixed-voltage regulators, these devices can be used with external components to obtain adjustable output voltages and currents and also as the power-pass element in precision regulators.

ORDERING INFORMATION†

TJ	V _O (NOM) (V)	PACKAGE [‡]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	0.0	PowerFLEX™ (KTP)	Reel of 3000	UA78M33QKTPRQ1	78M33CQ
3.3		SOT-223 (DCY)	23 (DCY) Reel of 2500 UA78M33QDCYRQ1		C3Q
	5	PowerFLEX™ (KTP)	Reel of 3000	UA78M05QKTPRQ1	78M05CQ
-40°C to 125°C		SOT-223 (DCY)	Reel of 2500	UA78M05QDCYRQ1	C5Q
	8	PowerFLEX™ (KTP)	Reel of 3000	UA78M08QKTPRQ1	78M08CQ
		SOT-223 (DCY)	Reel of 2500	UA78M08QDCYRQ1	C8Q
	10	PowerFLEX™ (KTP)	Reel of 3000	UA78M10QKTPRQ1	78M10CQ

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

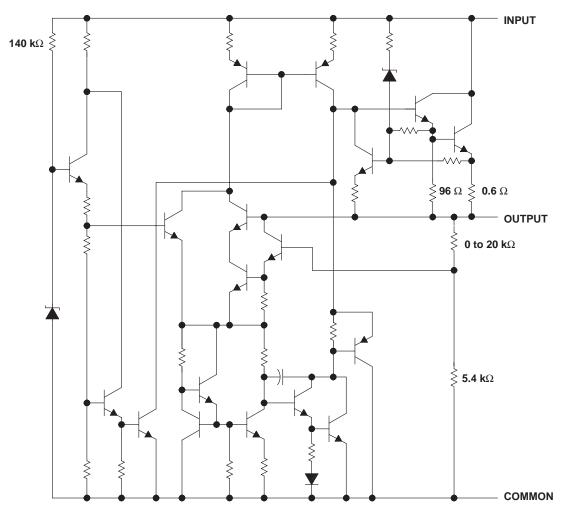
PowerFLEX is a trademark of Texas Instruments.



Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

SLVS537B – JUNE 2004 – REVISED SEPTEMBER 2008

schematic



Resistor values shown are nominal.



uA78Mxx-Q1 SERIES POSITIVE-VOLTAGE REGULATORS

SLVS537B - JUNE 2004 - REVISED SEPTEMBER 2008

absolute maximum ratings over virtual junction temperature range (unless otherwise noted)†

Input voltage, V _I	35 \
Operating virtual junction temperature, T _J	150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{stg}	-65°C to 150°C

package thermal data (see Note 1)

PACKAGE	BOARD	θЈС	θ JA
PowerFLEX (KTP)	High K, JESD 51-5	19°C/W	28°C/W
SOT-223 (DCY)	High K, JESD 51-7	4°C/W	53°C/W

NOTE 1: Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.

recommended operating conditions

			MIN	MAX	UNIT
		μΑ78Μ33	5.3	25	
		μΑ78Μ05	7	25	
		μΑ78Μ06	8	25	
VI	Input voltage	μA78M08	10.5	25	V
		μΑ78Μ09	11.5	26	
		μA78M10	12.5	28	
		μA78M12	14.5	30	
lo	Output current	•		500	mA
TJ	Operating virtual junction temperature		-40	125	°C



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

SLVS537B - JUNE 2004 - REVISED SEPTEMBER 2008

electrical characteristics at specified virtual junction temperature, V_I = 8 V, I_O = 350 mA, T_J = 25°C (unless otherwise noted)

	TEST SOURITIONS!			μ Α78M33Q			
PARAMETER	TES	ST CONDITIONS†	MIN	TYP	MAX	UNIT	
Output walks as †	$I_{O} = 5 \text{ mA to } 350 \text{ mA},$		3.2	3.3	3.4	V	
Output voltage‡	$V_{I} = 8 \text{ V to } 20 \text{ V}$	$T_J = -40^{\circ}C$ to 125°C	3.1	3.3	3.5	V	
Land and the man and affine	L 000 A	V _I = 5.3 V to 25 V		9	100		
Input voltage regulation	I _O = 200 mA	V _I = 8 V to 25 V		3	50	mV	
B. J	$V_{I} = 8 \text{ V to } 18 \text{ V},$	$I_{O} = 100 \text{ mA}, T_{J} = -40^{\circ}\text{C to } 125^{\circ}\text{C}$	62				
Ripple rejection	f = 120 Hz	I _O = 300 mA	62	80		dB	
Output voltage regulation	V _I = 8 V,	I _O = 5 mA to 500 mA		20	100	mV	
Temperature coefficient of output voltage	$I_O = 5 \text{ mA},$	$T_J = -40^{\circ}C$ to 125°C		-1		mV/°C	
Output noise voltage	f = 10 Hz to 100 kHz			40	200	μV	
Dropout voltage				2		V	
Bias current				4.5	6	mA	
Bias current change	$I_O = 200 \text{ mA},$ $T_J = -40^{\circ}\text{C to } 125^{\circ}\text{C}$	V _I = 8 V to 25 V,			0.8	mA	
_	$I_{O} = 5 \text{ mA to } 350 \text{ mA}, T_{J} = -40^{\circ}\text{C to } 125^{\circ}\text{C}$				0.5		
Short-circuit output current	V _I = 35 V			300		mA	
Peak output current				700		mA	

The All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output. Pulse-testing techniques maintain T_J as close to T_A as possible. Thermal effects must be taken into account separately.

electrical characteristics at specified virtual junction temperature, $V_I = 10 \text{ V}$, $I_O = 350 \text{ mA}$, $T_J = 25^{\circ}\text{C}$ (unless otherwise noted)

DADAMETED	TEST CONDITIONS†			μ Α78M05Q			
PARAMETER	TES	GI CONDITIONS!	MIN	TYP	MAX	UNIT	
Output walte as	$I_{O} = 5 \text{ mA to } 350 \text{ mA},$		4.8	5	5.2	V	
Output voltage	$V_{I} = 7 \text{ V to } 20 \text{ V}$	$T_J = -40^{\circ}C$ to $125^{\circ}C$	4.75		5.25	V	
lanut valta na va mulatia n	1 - 200 m A	V _I = 7 V to 25 V		3	100	>/	
Input voltage regulation	$I_O = 200 \text{ mA}$	V _I = 8 V to 25 V		1	50	mV	
Displanation	$V_{I} = 8 \text{ V to } 18 \text{ V},$	$I_{O} = 100 \text{ mA}, T_{J} = -40^{\circ}\text{C to } 125^{\circ}\text{C}$	62			-ID	
Ripple rejection	f = 120 Hz	I _O = 300 mA	62	80		dB	
Output walks are an adalised	I _O = 5 mA to 500 mA			20	100	mV	
Output voltage regulation	I _O = 5 mA to 200 mA			10	50		
Temperature coefficient of output voltage	$I_O = 5 \text{ mA},$	$T_J = -40^{\circ}C$ to $125^{\circ}C$		-1		mV/°C	
Output noise voltage	f = 10 Hz to 100 kHz			40	200	μV	
Dropout voltage				2		V	
Bias current				4.5	6	mA	
Bias current change	$I_{O} = 200 \text{ mA},$ $T_{J} = -40^{\circ}\text{C to } 125^{\circ}\text{C}$	V _I = 8 V to 25 V,			0.8	mA	
	$I_{O} = 5 \text{ mA to } 350 \text{ mA}, T_{J} = -40^{\circ}\text{C to } 125^{\circ}\text{C}$				0.5	5	
Short-circuit output current	V _I = 35 V			300		mA	
Peak output current				0.7		Α	

[†] All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output. Pulse-testing techniques maintain T_J as close to T_A as possible. Thermal effects must be taken into account separately.



[‡] This specification applies only for dc power dissipation permitted by absolute maximum ratings.

SLVS537B - JUNE 2004 - REVISED SEPTEMBER 2008

electrical characteristics at specified virtual junction temperature, $V_I = 14 \text{ V}$, $I_O = 350 \text{ mA}$, $T_J = 25^{\circ}\text{C}$ (unless otherwise noted)

24244555		μ Α78Μ08Q					
PARAMETER		MIN	TYP	MAX	UNIT		
Outside and	V. 40 5 V to 22 V	I- 5 A to 250 A		7.7	8	8.3	V
Output voltage	$V_I = 10.5 \text{ V to } 23 \text{ V},$	$I_O = 5 \text{ mA to } 350 \text{ mA}$	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$	7.6		8.4	V
land with a second of a		V _I = 10.5 V to 25 V			6	100	>/
Input voltage regulation	I _O = 200 mA	$V_{ } = 11 \text{ V to } 25 \text{ V}$			2	50	mV
5	$V_{I} = 11.5 \text{ V to } 21.5 \text{ V},$	I _O = 100 mA,	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$	56			- 15
Ripple rejection	f = 120 Hz	I _O = 300 mA		56	80		dB
Outrot will a serve and atten	I _O = 5 mA to 500 mA				25	160	>/
Output voltage regulation	I _O = 5 mA to 200 mA				10	80	mV
Temperature coefficient of output voltage	I _O = 5 mA,	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			-1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz				52		μV
Dropout voltage					2		V
Bias current					4.6	6	mA
5:	V _I = 10.5 V to 25 V,	I _O = 200 mA,	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			0.8	
Bias current change	I _O = 5 mA to 350 mA,	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$				0.5	mA
Short-circuit output current	V _I = 35 V				250		mA
Peak output current					0.7		Α

[†] All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output. Pulse-testing techniques maintain T_J as close to T_A as possible. Thermal effects must be taken into account separately.

electrical characteristics at specified virtual junction temperature, $V_I = 17 \text{ V}$, $I_O = 350 \text{ mA}$, $T_J = 25^{\circ}\text{C}$ (unless otherwise noted)

DADAMETED		μ Α78M10Q						
PARAMETER		TEST CONDITIONS†					UNIT	
Output well-and	V. 40.5 V. 40.05 V.	I- 5 A to 250 A		9.6	10	10.4	V	
Output voltage	$V_I = 12.5 \text{ V to } 25 \text{ V},$	$I_O = 5 \text{ mA to } 350 \text{ mA}$	$T_J = -40^{\circ}C$ to $125^{\circ}C$	9.5		10.5	V	
Land calleng as acted as		V _I = 12.5 V to 28 V			7	100	>/	
Input voltage regulation	I _O = 200 mA	V _I = 14 V to 28 V			2	50	mV	
Disable asis office	V _I = 15 V to 25 V,	I _O = 100 mA,	$T_J = -40^{\circ}C$ to $125^{\circ}C$	59			10	
Ripple rejection	f = 120 Hz	IO = 300 mA		55	80		dB	
Output wells as as addition	$I_O = 5$ mA to 500 mA				25	200	>/	
Output voltage regulation	I _O = 5 mA to 200 mA				10	100	mV	
Temperature coefficient of output voltage	I _O = 5 mA,	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			-1		mV/°C	
Output noise voltage	f = 10 Hz to 100 kHz				64		μV	
Dropout voltage					2		V	
Bias current					4.7	6	mA	
	$V_I = 12.5 \text{ V to } 28 \text{ V},$	I _O = 200 mA,	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			0.8		
Bias current change	$I_{O} = 5$ mA to 350 mA, $T_{J} = -40^{\circ}$ C to 125°C					0.5	mA	
Short-circuit output current	V _I = 35 V				245		mA	
Peak output current					0.7		Α	

[†] All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output. Pulse-testing techniques maintain T_J as close to T_A as possible. Thermal effects must be taken into account separately.





PACKAGE OPTION ADDENDUM

www.ti.com 28-May-2009

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
UA78M05QDCYRG4Q1	ACTIVE	SOT-223	DCY	4	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UA78M05QKTPRQ1	OBSOLETE	PFM	KTP	2		TBD	Call TI	Call TI
UA78M33QDCYRG4Q1	ACTIVE	SOT-223	DCY	4	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UA78M33QKTPRQ1	OBSOLETE	PFM	KTP	2		TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF UA78M05-Q1, UA78M33-Q1:

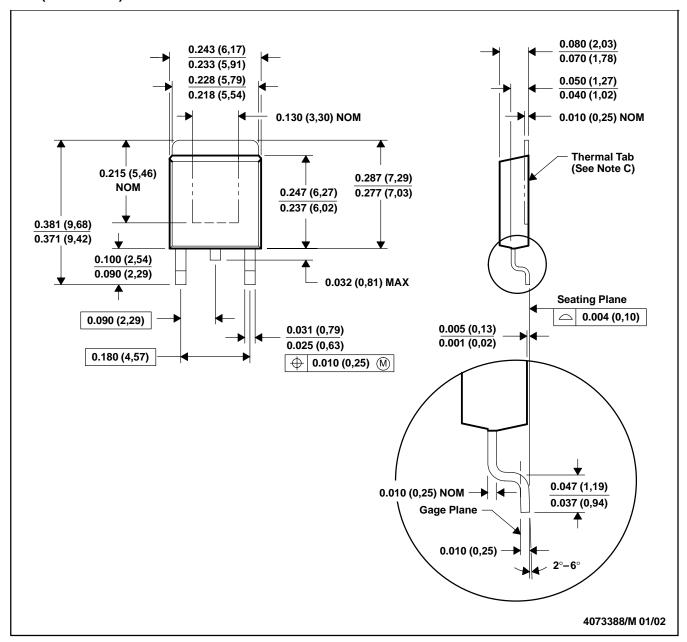
• Catalog: UA78M05, UA78M33

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

KTP (R-PSFM-G2)

PowerFLEX™ PLASTIC FLANGE-MOUNT PACKAGE



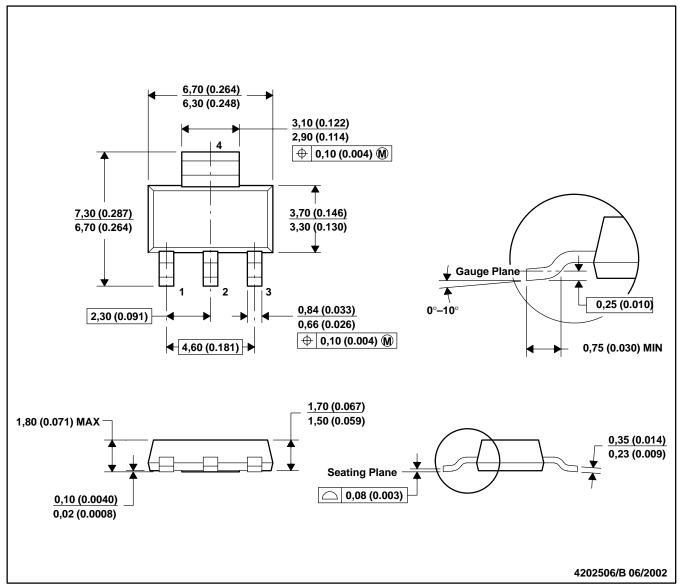
- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. The center lead is in electrical contact with the thermal tab.
 - D. Dimensions do not include mold protrusions, not to exceed 0.006 (0,15).
 - E. Falls within JEDEC TO-252 variation AC.

PowerFLEX is a trademark of Texas Instruments.



DCY (R-PDSO-G4)

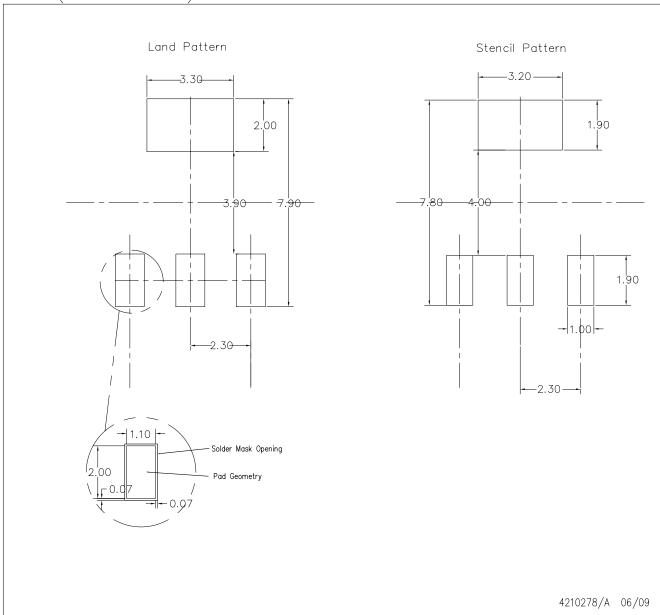
PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters (inches).

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC TO-261 Variation AA.

DCY (R-PDSO-G4)



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations.



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